3.3V, Crystal-to-HCSL Clock Generator

Description

The NB3N5573 is a high precision, low phase noise clock generator that supports PCI Express and Ethernet requirements. The device takes a 25 MHz fundamental mode parallel resonant crystal and generates differential HCSL output at 25 MHz, 100 MHz, 125 MHz or 200 MHz clock frequencies. Outputs can interface with LVDS with proper termination (See Figure 4).

This device is housed in 5.0 mm x 4.4 mm narrow body TSSOP 16 pin package.

Features

- Uses 25 MHz Fundamental Mode Parallel Resonant Crystal
- External Loop Filter is Not Required
- HCSL Differential Output or LVDS with Proper Termination
- Phase Noise:

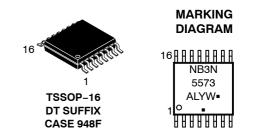
Offset Noise Power 100 Hz -103 dBc/Hz 1 kHz -118 dBc/Hz 10 kHz -122 dBc/Hz 100 kHz -130 dBc/Hz 1 MHz -132 dBc/Hz 10 MHz -149 dBc/Hz

- Typical Period Jitter RMS of 1.5 ps
- Operating Range 3.3 V ±10%
- Industrial Temperature Range -40°C to +85°C
- These are Pb-Free Devices



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A = Assembly Location

L = Wafer Lot
 Y = Year
 W = Work Week

= Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

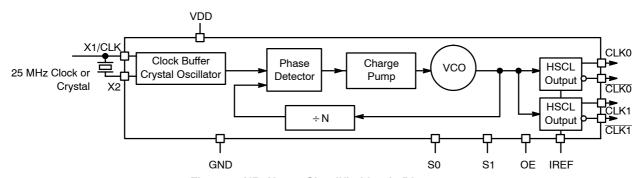


Figure 1. NB3N5573 Simplified Logic Diagram

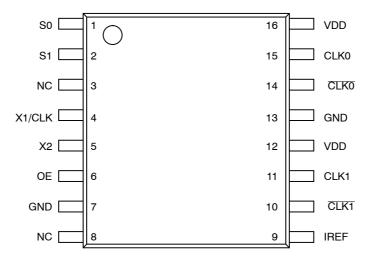


Figure 2. Pin Configuration (Top View)

Table 1. PIN DESCRIPTION

Pin	Symbol	I/O	Description
1	S0	Input	LVTTL/LVCMOS frequency select input 0. Internal pullup resistor to V_{DD} . See output select table 2 for details.
2	S1	Input	LVTTL/LVCMOS frequency select input 1. Internal pullup resistor to V _{DD} . See output select Table 2 for details.
12, 16	V_{DD}	Power Supply	Positive supply voltage pins are connected to +3.3 V supply voltage.
4	X1/CLK	Input	Crystal or Clock input. Connect to 25 MHz crystal source or single-ended clock.
5	X2	Input	Crystal input. Connect to a 25 MHz crystal or leave unconnected for clock input.
6	OE	Input	Output enable tri-states output when connected to GND. Internal pullup resistor to V _{DD} .
7, 13	GND	Power Supply	Ground 0 V. These pins provide GND return path for the devices.
9	I _{REF}	Output	Output current reference pin. Precision resistor (typ. 475 Ω) is connected to set the output current.
11	CLK1	HCSL or LVDS Output	Noninverted clock output. (For LVDS levels see Figure 4)
10	CLK1	HCSL or LVDS Output	Inverted clock output. (For LVDS levels see Figure 4)
15	CLK0	HCSL or LVDS Output	Noninverted clock output. (For LVDS levels see Figure 4)
14	CLK0	HCSL or LVDS Output	Inverted clock output. (For LVDS levels see Figure 4)
3, 8	NC		Do not connect

Table 2. OUTPUT FREQUENCY SELECT TABLE

S1	S0	f _{CLKout} (MHz)
L	L	25
L	Н	100
Н	L	125
Н	Н	200

Recommended Crystal Parameters

Crystal	Fundamental AT–Cut
Frequency	25 MHz
Load Capacitance	16-20 pF
Shunt Capacitance, C0	7 pF Max
Equivalent Series Resistance	35 Ω Max
Initial Accuracy at 25 °C	±20 ppm
Temperature Stability	±30 ppm
Aging	±20 ppm
C0/C1 Ration	250 Max

Table 3. ATTRIBUTES

Charac	Value	
ESD Protection	Human Body Model	> 2 kV
Moisture Sensitivity, Indefinite Ti	Level 1	
Flammability Rating	UL 94 V-0 @ 0.125 in	
Transistor Count	7623	
Meets or exceeds JEDEC Spec		

^{1.} For additional information, see Application Note AND8003/D.

Table 4. MAXIMUM RATINGS (Note 2)

Symbol	Parameter	Condition 1	Condition 2	Rating	Units
V_{DD}	Positive Power Supply	GND = 0 V		4.6	V
VI	Input Voltage (V _{IN})	GND = 0 V	$GND \le V_I \le V_{DD}$	-0.5 V to V _{DD} +0.5 V	V
T _A	Operating Temperature Range			-40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	TSSOP-16 TSSOP-16	138 108	°C/W °C/W
θJC	Thermal Resistance (Junction-to-Case)	(Note 3)	TSSOP-16	33 to 36	°C/W
T _{sol}	Wave Solder			265	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 5. DC CHARACTERISTICS (V_{DD} = 3.3 V ±10%, GND = 0 V, T_A = -40°C to +85°C, Note 4)

Symbol	Characteristic	Min	Тур	Max	Unit
VDD	Power Supply Voltage	2.97	3.3	3.63	V
I _{DD}	Power Supply Current		120	135	mA
I _{DDOE}	Power Supply Current when OE is Set Low			65	mA
V _{IH}	Input HIGH Voltage (X/CLK, S0, S1, and OE)	2000		V _{DD} + 300	mV
V _{IL}	Input LOW Voltage (X/CLK, S0, S1, and OE)	GND - 300		800	mV
V _{OH}	Output HIGH Voltage for HCSL Output (See Figure 5)	660	700	850	mV
V _{OL}	Output LOW Voltage for HCSL Output (See Figure 5)	-150	0	150	mV
V _{cross}	Crossing Voltage Magnitude (Absolute) for HCSL Output	250		550	mV
ΔV_{cross}	Change in Magnitude of V _{cross} for HCSL Output			150	mV

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

^{2.} Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and not valid simultaneously. If stress limits are exceeded device functional operation is not implied, damage may occur and reliability may be affected.

^{3.} JEDEC standard multilayer board – 2S2P (2 signal, 2 power).

^{4.} Measurement taken with outputs terminated with R_S = 33.2 Ω , R_L = 49.9 Ω , with test load capacitance of 2 pF and current biasing resistor set at 475 Ω . See Figure 3.

Table 6. AC CHARACTERISTICS (V_{DD} = 3.3 V ±10%, GND = 0 V, T_A = -40°C to +85°C; Note 5)

Symbol	Characteristic	Min	Тур	Max	Unit
f _{CLKIN}	Clock/Crystal Input Frequency		25		MHz
fclkout	Output Clock Frequency	25		200	MHz
Ω_{NOISE}	Phase–Noise Performance f _{CLKout} = 200 MHz				dBc/Hz
	@ 100 Hz offset from carrier		-103		
	@ 1 kHz offset from carrier		-118		
	@ 10 kHz offset from carrier		-122		
	@ 100 kHz offset from carrier		-130		
	@ 1 MHz offset from carrier		-132		
	@ 10 MHz offset from carrier		-149		
T _{jitter}	Period Jitter Peak-to-Peak (Note 6) f _{CLKout} = 200 MHz		10	20	ps
	Period Jitter RMS (Note 6) f _{CLKout} = 200 MHz		1.5	3	
	Cycle-Cycle RMS Jitter (Note 7) f _{CLKout} = 200 MHz		2	5	
	Cycle-to-Cycle Peak to Peak Jitter (Note 7) f _{CLKout} = 200 MHz		20	35	ps
OE	Output Enable/Disable Time		10		μs
t _{DUTY_CYCLE}	Output Clock Duty Cycle (Measured at cross point)	45	50	55	%
t _R	Output Risetime (Measured from 175 mV to 525 mV, Figure 5)	175	340	700	ps
t _F	Output Falltime (Measured from 525 mV to 175 mV, Figure 5)	175	340	700	ps
Δt_R	Output Risetime Variation (Single-Ended)			125	ps
Δt_{F}	Output Falltime Variation (Single-Ended)			125	ps
Stabilization Time	Stabilization Time From Powerup V _{DD} = 3.3 V		3.0		ms

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 5. Measurement taken from differential output on single–ended channel terminated with $R_S = 33.2 \Omega$, $R_L = 49.9 \Omega$, with test load capacitance of 2 pF and current biasing resistor set at 475 Ω . See Figure 3.
- 6. Sampled with 10000 cycles.
- 7. Sampled with 1000 cycles.

HCSL INTERFACE

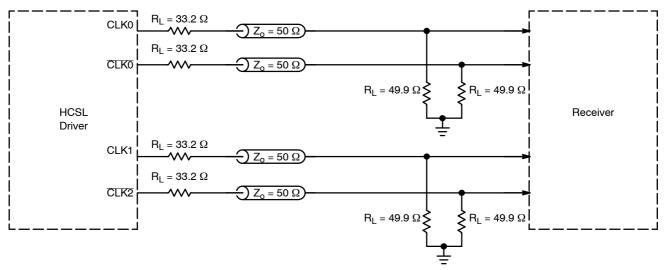


Figure 3. Typical Termination for Output Driver and Device Evaluation

LVDS COMPATIBLE INTERFACE

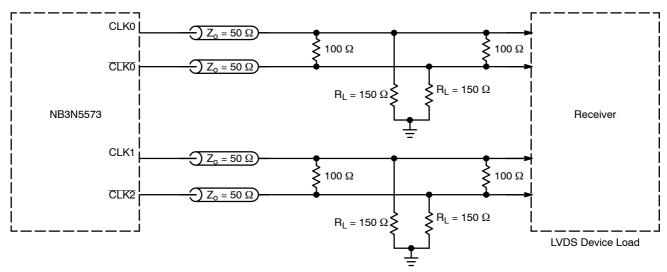
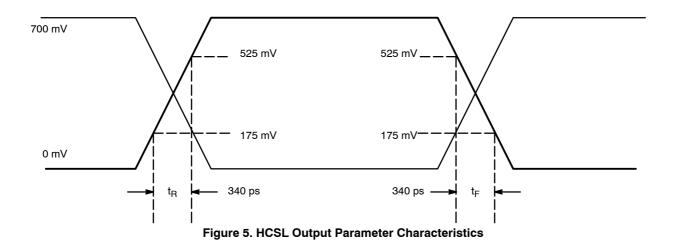


Figure 4. Typical Termination for LVDS Device Load



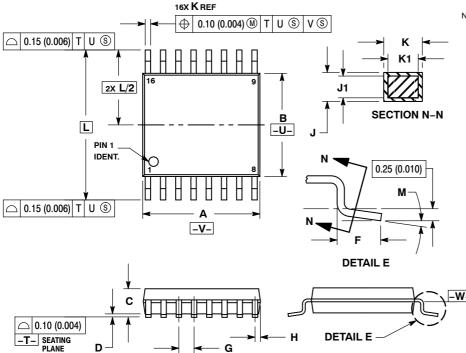
ORDERING INFORMATION

Device	Package	Shipping [†]
NB3N5573DTG	TSSOP-16 (Pb-Free)	96 Units / Rail
NB3N5573DTR2G	TSSOP-16 (Pb-Free)	2500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

TSSOP-16 CASE 948F-01 **ISSUE B**



NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: MILLIMETER.

 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT TYCED ALS (DOES DEED SIDE
- MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

 DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION.

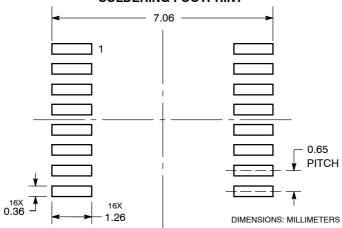
 INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

 DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.

 TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
- REFERENCE ONLY.
 DIMENSION A AND B ARE TO BE
- DETERMINED AT DATUM PLANE -W-.

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	4.90	5.10	0.193	0.200	
В	4.30	4.50	0.169	0.177	
С		1.20		0.047	
D	0.05	0.15	0.002	0.006	
F	0.50	0.75	0.020	0.030	
G	0.65 BSC		0.026 BSC		
Н	0.18	0.28	0.007	0.011	
J	0.09	0.20	0.004	0.008	
J1	0.09	0.16	0.004	0.006	
K	0.19	0.30	0.007	0.012	
K1	0.19	0.25	0.007	0.010	
L	6.40 BSC		0.252	BSC	
М	0°	8°	0°	8°	

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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